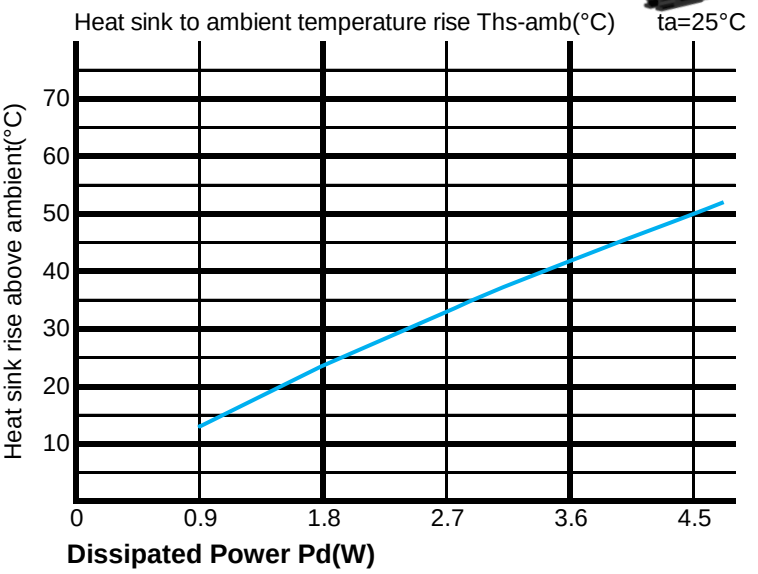
FanLED **FanLED-38 Series Φ38mm Material AL6063-T5 COB Star Heat Sinks Thermal Data**

The thermal data table

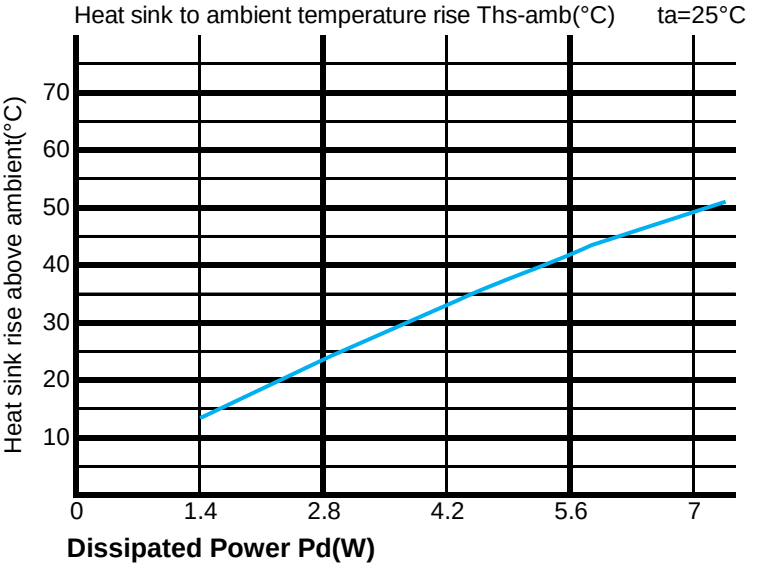
Fan-3820 thermal data

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
		FanLED-3820	FanLED-3820
Dissipated Power Pd(W)	0.9	15.4	14
	1.8	13.4	24.5
	2.7	12.4	34
	3.6	11.4	42
	4.5	10.9	50



Fan-3850 thermal data

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
		FanLED-3850	FanLED-3850
Dissipated Power Pd(W)	1.4	9.8	14
	2.8	8.4	24
	4.2	7.7	33.2
	5.6	7.2	41.6
	7	6.9	49.5



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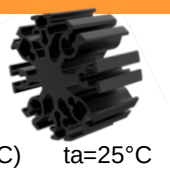
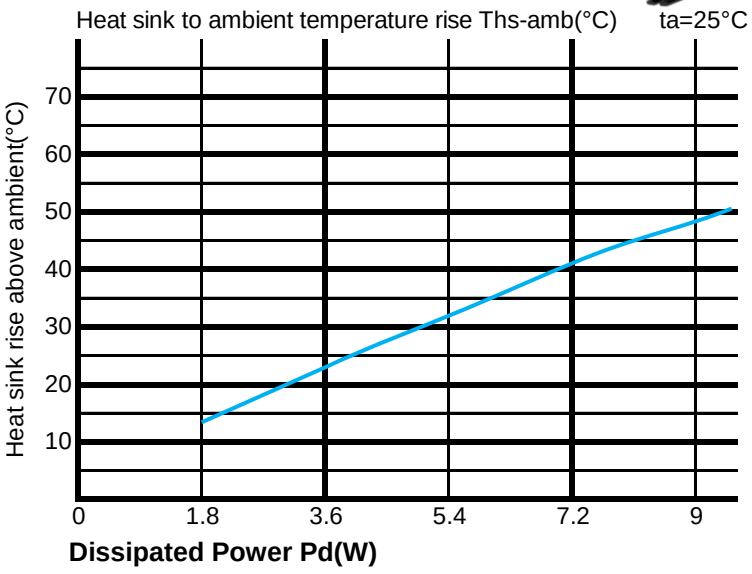
FanLED-38 Series Φ38mm Material AL6063-T5 COB Star Heat Sinks Thermal Data

The thermal data table



Fan-3880 thermal data

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
		FanLED-3880	FanLED-3880
Dissipated Power Pd(W)	1.8	7.2	13.4
	3.6	6.5	24
	5.4	5.9	33
	7.2	5.5	41
	9	5.2	49



* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

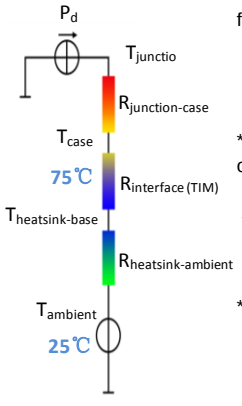
*To calculate the dissipated power please use the following formula: Pd = Pe x (1-ηL).

Pd - Dissipated power ; Pe - Electrical power ; ηL = Light effciency of the LED module;

*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease,A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula: θ =(Ths−Ta)/Pd

θ - Thermal Resistance [°C/W] ; Ths - Heatsink temperature ; Ta - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface\ (TIM)}$ [°C/W], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ [°C/W], and the ambient temperature is $T_{ambient}$ [°C].

*Thermal resistances outside the package $R_{interface\ (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point.Thus, the following formula is also used:

$T_{junction}=(R_{junction-case}+R_{case-ambient})\cdot Pd+T_{ambient}$

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